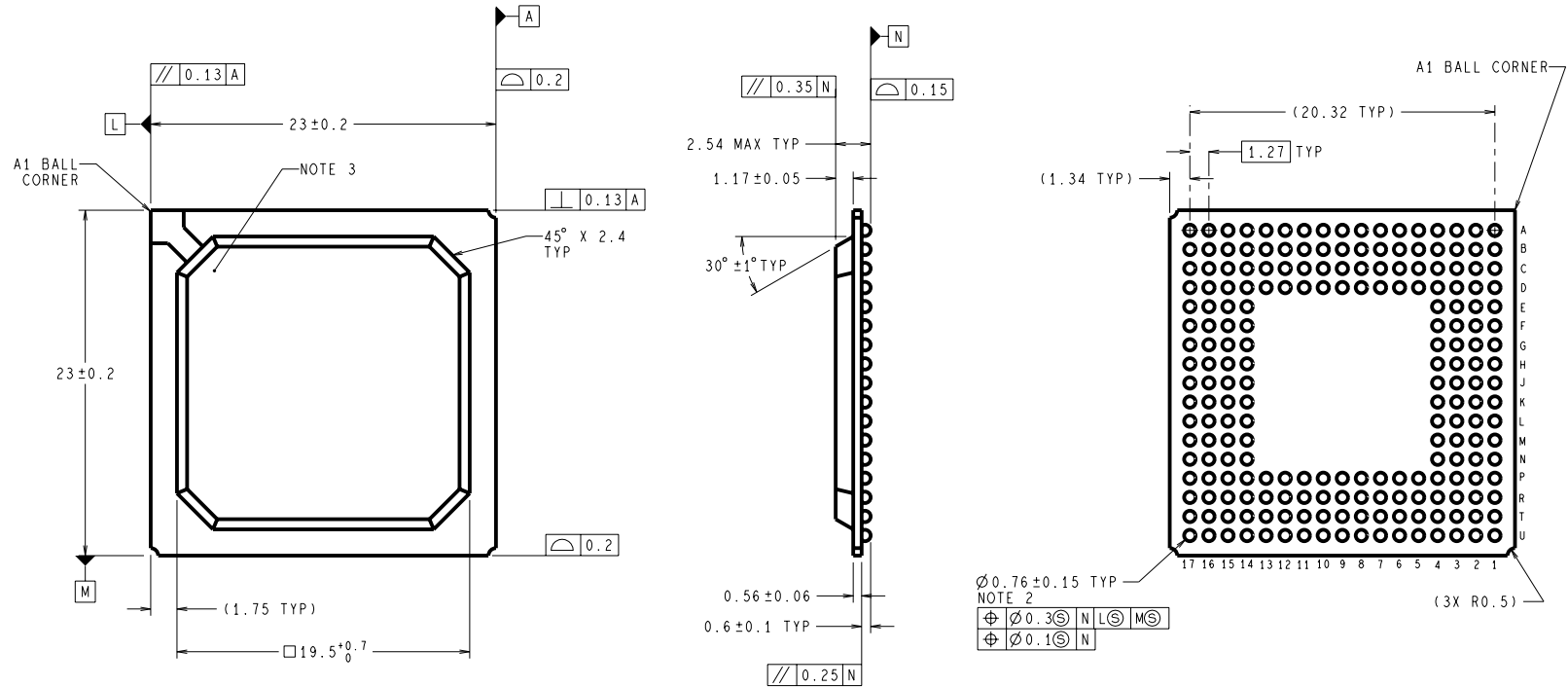


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11837	01/15/1998	MS/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. THE MOLD SURFACE AREA MAY INCLUDE DIMPLE FOR A1 BALL CORNER IDENTIFICATION.
4. REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27 PITCH, DATED JUNE, 1997.
5. REFERENCE ANAM DRAWING 71244, DATED 5/15/1996.

APPROVALS		DATE	National Semiconductor		
DRWN:	MARTA SUCHY	01/05/1998	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DTG. CHK.			PBGA, 23.0 X 23.0mm BODY, 208 BALL, 1.27mm PITCH		
ENGR. CHK.					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-UDC208A	A
DO NOT SCALE DRAWING			SHEET 1 of 1		